

MATERIAL DECLARATION SHEET



Material Number	CM453232 Series(R10-121)			
Product Line	Wound Chip Inductor			
Compliance Date	01/01/2005			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ferrite Material	Ferrite	0.03	Iron oxide	1309-37-1	63.0	17.17	27.273
				Nickel oxide	1313-99-1	12.0	3.27	
				Zinc oxide	1314-13-2	18.0	4.91	
				Copper oxide	1317-38-0	7.0	1.91	
2	Winding Wire	Copper	0.016	Copper	7440-50-8	95.0	13.82	14.546
				Polyesterimide	37317-16-1	5.0	0.73	
3	Terminal	Copper	0.035	Copper	7440-50-8	95.0	30.23	31.818
				Tin	7440-31-5	5.0	1.59	
4	Adhesive	Resin	0.015	Epoxy resin	25068-38-6	69.1	9.42	13.636
				Dicyanodiamide	461-58-5	6.4	0.87	
				Titanium dioxide	13463-67-7	4.3	0.59	
				Silicon dioxide	731-86-9	20.2	2.75	

MATERIAL DECLARATION SHEET

BOURNS®

6	Molding Compound	Silica	0.01	Silicon dioxide	60676-86-0	69.0	6.27	9.091
				Antimony trioxide	1309-64-4	2.5	0.23	
				Phenol-formaldehyde Resin	29690-82-2	15.0	1.36	
				Phenol-Formaldehyde Resin	9003-35-4	10.0	0.91	
				Brominated epoxy resin	40039-93-8	2.5	0.23	
				Carbon black	1333-86-4	1.0	0.09	
7	Solder	Tin	0.004	Tin	7440-31-5	100.0	3.64	3.636
		Total weight	0.11					

This Document was updated on: 2020/12/24

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.